

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-5. (Canceled)

6. (Previously Presented) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface including at least one unit each having a plurality of semiconductor element mount regions defined thereon;

a mask disposed on the second planar surface and having respective patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, said mask comprising a conductive film, and

guide holes into which guide pins are inserted,

wherein each unit includes a plurality of first pads defined by the respective patterns in the unit and a plurality of die pads defined by the respective semiconductor element mount regions in the unit,

wherein the conductive film is disposed in the semiconductor element mount regions to form the die pads.

7-15. (Canceled)

16. (Previously Presented) A sheet-like board member comprising:  
a first planar surface;  
a second planar surface disposed opposite to the first planer surface, the second surface including at least one unit each of which includes protuberances and semiconductor mount regions formed on said second planar surface; and  
guide holes into which guide pins are inserted,  
wherein the protuberances define a plurality of first pads in or in the vicinity of the semiconductor element mount regions defined on the second planar surface , and  
wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit,  
wherein the protuberances comprise the die pads provided in the semi-conductor element mount region.

17-37. (Canceled)

38. (Previously Presented) A sheet-like board member comprising:  
a first planar surface;  
a second planar surface disposed opposite to the first surface, said second planar surface having at least one unit each of which has semiconductor element mount regions defined thereon;  
a mask for etching disposed on the second planar surface and having patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, wherein each unit comprises a plurality of the patterns, and  
guide holes into which guide pins are inserted,  
wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit,  
wherein the mask comprises a conductive film

wherein the conductive film is disposed in the semiconductor element mount region to form a die pad.

39-61. (Canceled)

62. (Previously Presented) A method of manufacturing a semiconductor device comprising:

preparing a sheet-like board member as defined in claim 6;

partially etching the second planar surface of the sheet-like member so as to form the first pads;

disposing a circuit element onto a portion on the sheet-like board member;

molding a surface of the sheet-like board member by an insulating resin so that the sheet-like board member is covered,

wherein the sheet-like board member is fixed by means of vacuum suction.

63. (Canceled)

64. (Currently Amended) A method of manufacturing a semiconductor device comprising:

preparing a sheet-like board member as defined in ~~any one of claims~~ claim 16 and 54;

disposing a circuit element onto a portion of the protuberances of the sheet-like board member;

molding a surface of the sheet-like board member by an insulating plastic so that the sheet-like board member is covered,

wherein the sheet-like board member is fixed by means of vacuum suction.

65-75. (Canceled)

76. (New) A method of manufacturing a semiconductor device comprising:  
preparing a sheet-like board member, wherein the sheet-like board member comprises:

a planar surface defining at least one unit;

a sheet-like front side of predetermined thickness which is provided on the  
planar surface;

a plurality of first pads formed in each unit in or in the vicinity of  
semiconductor element mount regions defined in each unit on the planar surface;

protuberances in each unit formed on said planar surface and including  
wirings integrally formed with the first pads, said plurality of first pads and said  
protuberances formed within an abutting region defined on said planar surface,  
said abutting region provided to contact with an upper metal mold; and  
guide holes into which guide pins are inserted

wherein each unit includes a plurality of die pads defined by the respective  
semiconductor mount regions in the unit, and

wherein a positioning mark is provided on the sheet-like board member;  
disposing a circuit element onto a portion of the protuberances of the sheet-like board  
member;

molding a surface of the sheet-like board member by an insulating plastic so that the  
sheet-like board member is covered,

wherein the sheet-like board member is fixed by means of vacuum suction.